

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	235	((438/for.438) or (257/e23.018) or (257/e21.514)).CCLS.	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/10 09:27
L2	60514	bond\$3 with (substrate or wafer)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/10 09:27
L3	32	1 and 2	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/10 09:27
S1	1523	((438/456) or (438/118)).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2004/12/09 11:09
S2	23	S1 and ((inject injected injecting) with (conductor conductive))	US-PGPUB; USPAT	OR	ON	2004/12/07 14:54
S3	235	((438/for.438) or (257/e23.018) or (257/e21.514)).CCLS.	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/10 09:26
S4	0	S3 and ((inject injected injecting) with (conductor conductive))	USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/07 14:40
S5	9	(("5739585") or ("6163463") or ("6279596") or ("6341418") or ("6386422") or ("6426241") or ("6452117") or ("6459150") or ("6461136")).PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2004/12/07 14:41
S6	11	S1 and ((injection) with (conductor conductive))	US-PGPUB; USPAT	OR	ON	2004/12/07 15:10
S7	1542	gruber.inv.	US-PGPUB; USPAT	OR	ON	2004/12/07 15:10
S8	233	S7 and injection	US-PGPUB; USPAT	OR	ON	2004/12/07 15:11
S9	1	("6279596").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2004/12/07 15:11
S10	8	("4412642" "5244143" "5454159" "5718361" "5961032" "6025649" "6180504" "6186216").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2004/12/07 15:14
S11	0	("6459150").URPN.	USPAT	OR	ON	2004/12/08 08:38
S12	2	("6461136").URPN.	USPAT	OR	ON	2004/12/08 08:38
S13	7	("5468681" "5529504" "5719438" "5798469" "5959356" "6139661" "6396153").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2004/12/08 08:39

S14	34719	(injection or injecting) with (metal or conductive or conductor)	US-PGPUB; USPAT; USOCR	OR	ON	2004/12/08 08:40
S15	6620	S14 and semiconductor	US-PGPUB; USPAT; USOCR	OR	ON	2004/12/08 08:40
S16	1105	S15 and "438".clas.	US-PGPUB; USPAT; USOCR	OR	ON	2004/12/08 08:40
S17	277	S16 and ((bond or bonding or bonded) with (substrate or wafer))	US-PGPUB; USPAT; USOCR	OR	ON	2004/12/08 08:41
S18	2001	((438/118) or (438/119) or (438/456) or (438/610) or (438/661)).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2004/12/09 11:12
S19	1384	S18 and ((bond\$3 with (wafer or substrate)) and (inject\$3 with conductive))	US-PGPUB; USPAT	OR	ON	2004/12/09 11:13
S20	355	S19 and cavity	US-PGPUB; USPAT	OR	ON	2004/12/09 11:36
S21	235	((438/for.438) or (257/e21.514) or (257/e23.018)).CCLS.	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/09 11:36
S22	0	S21 and (inject\$4 with (conductor conductive))	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/09 11:37